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(12) **United States Design Patent** Alfredsson et al. (10) **Patent No.:** **US D914,624 S**
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(54) **ELECTRONIC DEVICE HOUSING**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/184**; D13/110; D13/123

(58) **Field of Classification Search**
USPC D13/110, 123, 158, 162, 184, 199;
D14/301, 439
CPC G05B 9/02; G05B 19/05; G05B 19/054;
G05B 19/056; G06F 1/182; G06F 1/183;
H05K 7/1462; H05K 7/1467; H05K
7/1474

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D348,269 S * 6/1994 Chong D13/184
D373,362 S * 9/1996 Kuroiwa D13/184
D424,529 S * 5/2000 Raspotnig D13/184
D437,586 S * 2/2001 Sonntag D13/184
D493,771 S * 8/2004 Pagella D13/110
D506,977 S * 7/2005 Lee D13/110

D643,376 S * 8/2011 Naumann D13/160
D702,198 S * 4/2014 Gretz D13/184
D707,187 S * 6/2014 Mauchle D13/162
D719,105 S * 12/2014 Shin D13/159
D762,495 S * 8/2016 Tanaka D10/50
D772,171 S * 11/2016 Ohmori D13/158
D823,798 S * 7/2018 Gleave D13/110
D860,957 S * 9/2019 Gao D13/184
D867,304 S * 11/2019 Tsurumi D13/159
10,547,161 B1 * 1/2020 Lin H02B 1/305
D877,701 S * 3/2020 Byrne D13/139.4
10,707,768 B2 * 7/2020 Voegeli H05K 7/20009
2004/0008492 A1 * 1/2004 Kato G05B 19/0421
361/715
2011/0222244 A1 * 9/2011 Takashiro H05K 7/1432
361/704

(Continued)

OTHER PUBLICATIONS

ABB Launches new microgrid system to boost use of renewables;
Oct. 10, 2016; 1 pg.; <https://www.windpowerengineering.com/abb-launches-new-microgrid-system-boost-use-renewables/>*

(Continued)

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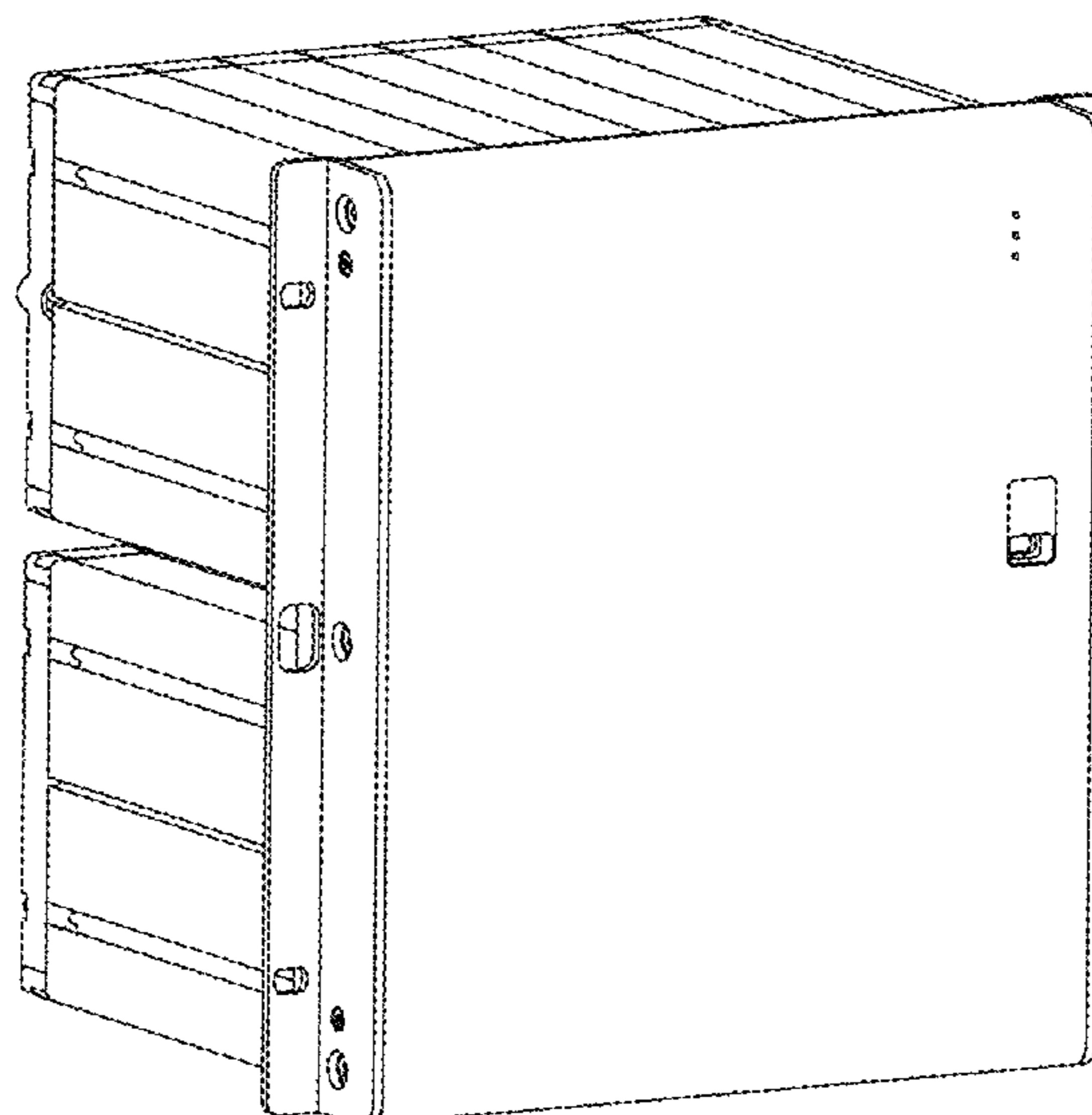
(57) **CLAIM**

The ornamental design for a electronic device housing, as shown and described.

DESCRIPTION

FIG. 1 is a top, front isometric view of a electronic device housing in accordance with the new design; FIG. 2 is a right side elevational view of FIG. 1; FIG. 3 is a left side elevational view of FIG. 1; FIG. 4 is a front elevational view of FIG. 1; FIG. 5 is a rear elevational view of FIG. 1; FIG. 6 is a top plan view of FIG. 1; and, FIG. 7 is a bottom plan view of FIG. 1.

1 Claim, 7 Drawing Sheets



(56)

References Cited

U.S. PATENT DOCUMENTS

2011/0242770 A1* 10/2011 Yamanaka H05K 7/1432
361/728
2013/0016481 A1* 1/2013 Takahashi H05K 7/20418
361/724
2019/0165687 A1* 5/2019 Yamazawa B32B 15/082
2020/0059163 A1* 2/2020 Koshii H02M 7/003

OTHER PUBLICATIONS

Rolls-Royce and ABB partner to develop micogrid solution for business; Apr. 2, 2019; 1 pg.; <https://www.edie.net/news/8/Rolls-Royce-and-ABB-partner-to-develop-microgrid-solution-for-business/>.*

* cited by examiner

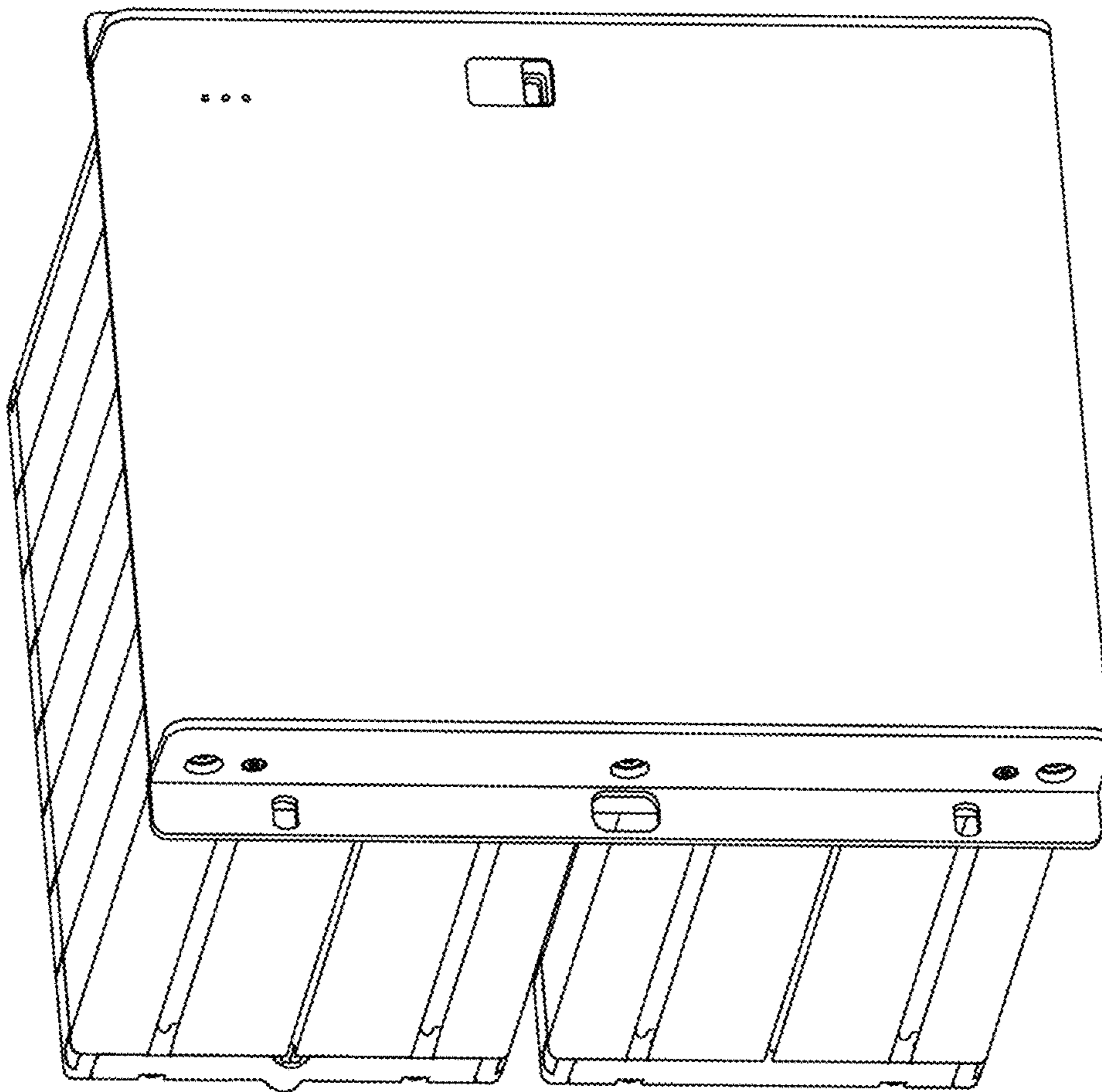


FIG. 1

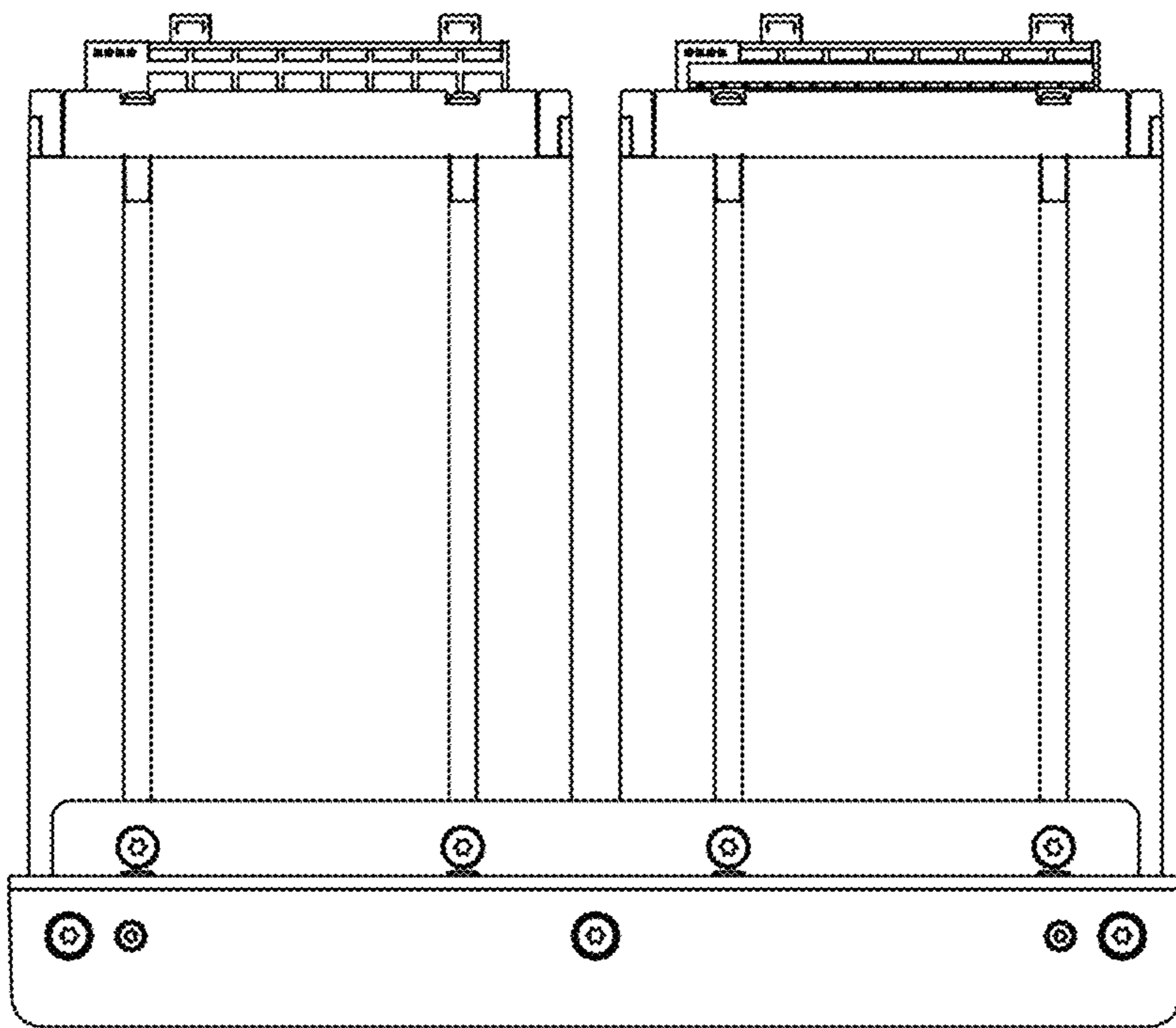


FIG. 2

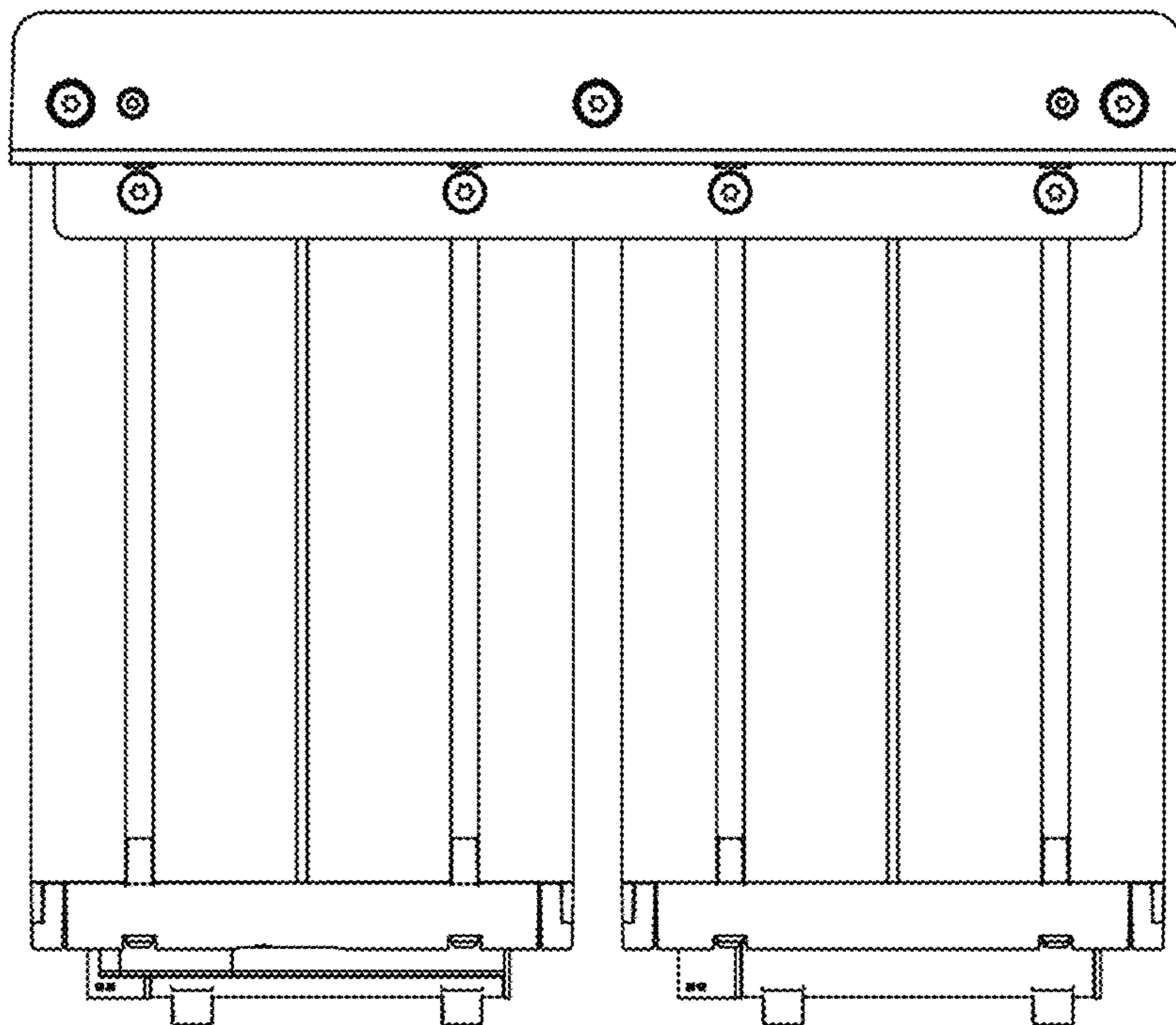


FIG. 3

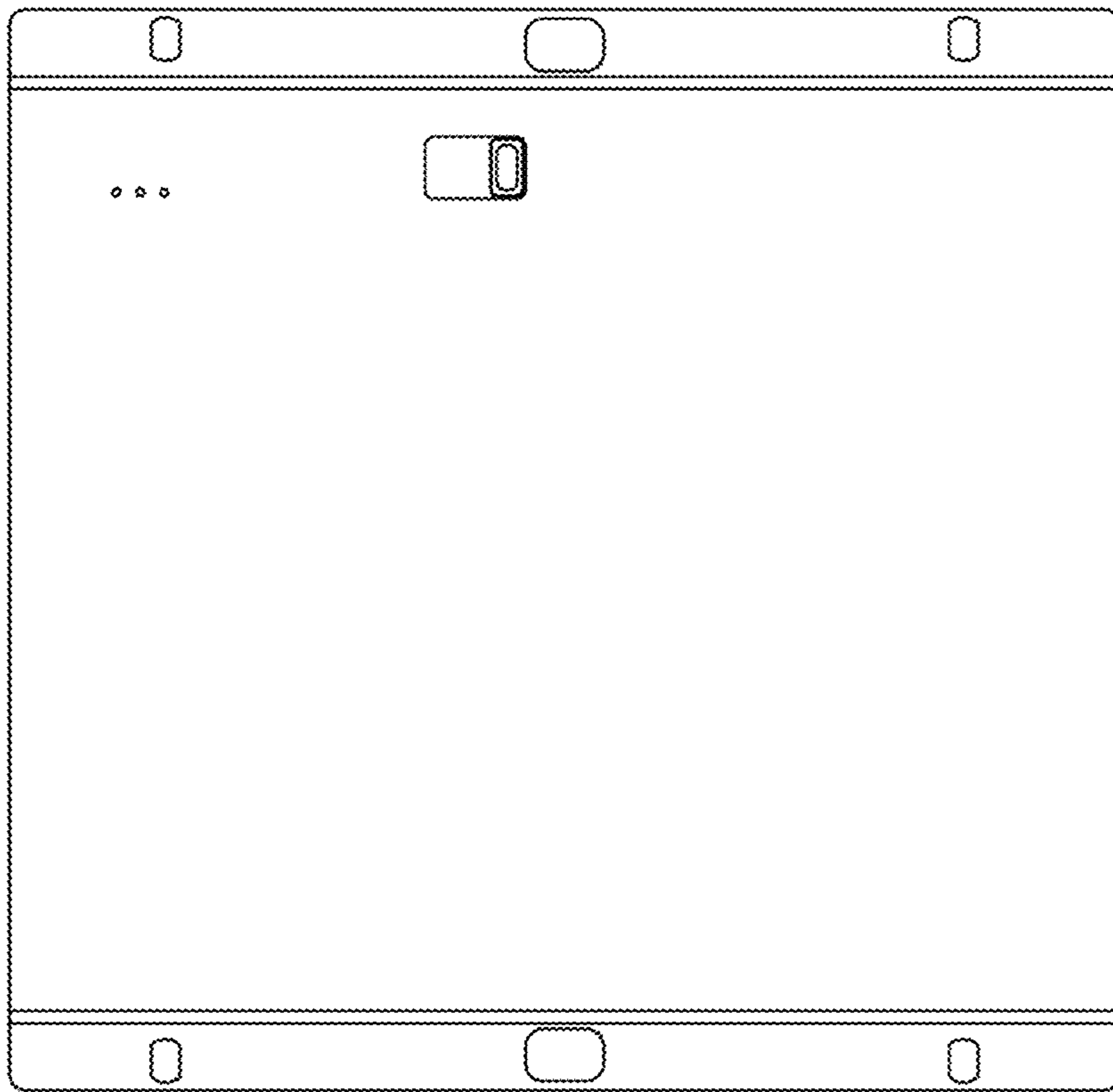


FIG. 4

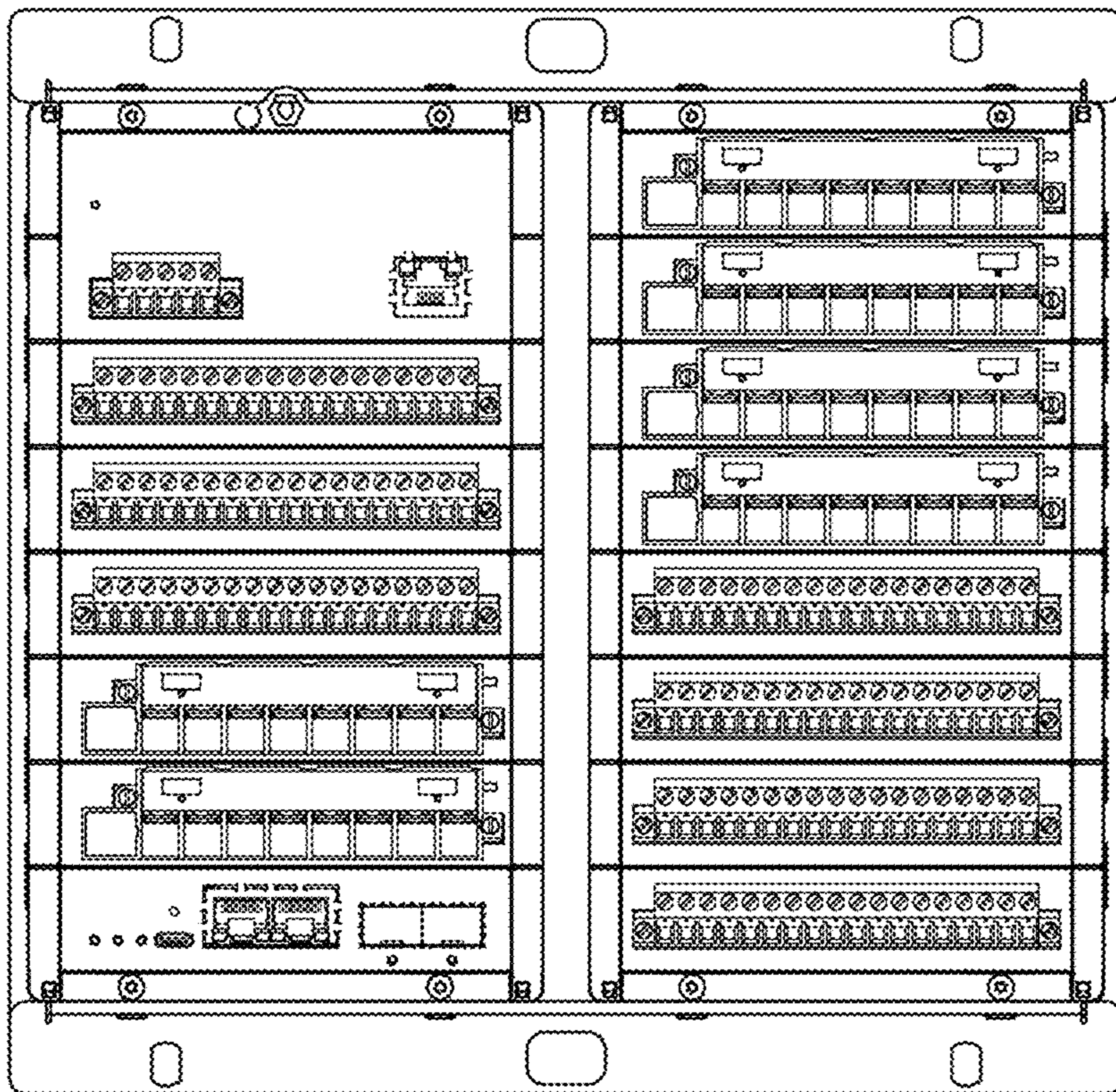


FIG. 5

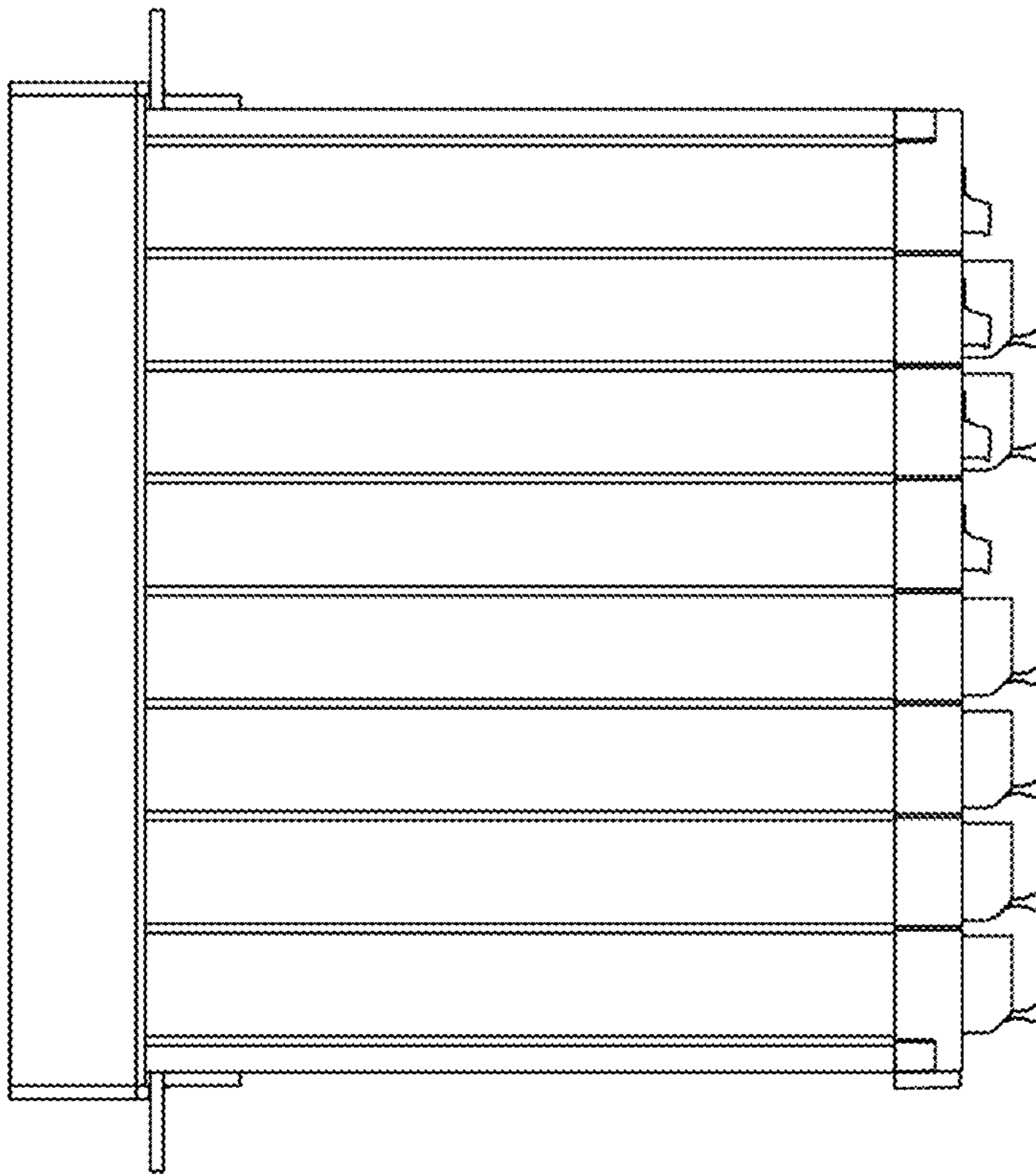


FIG. 6

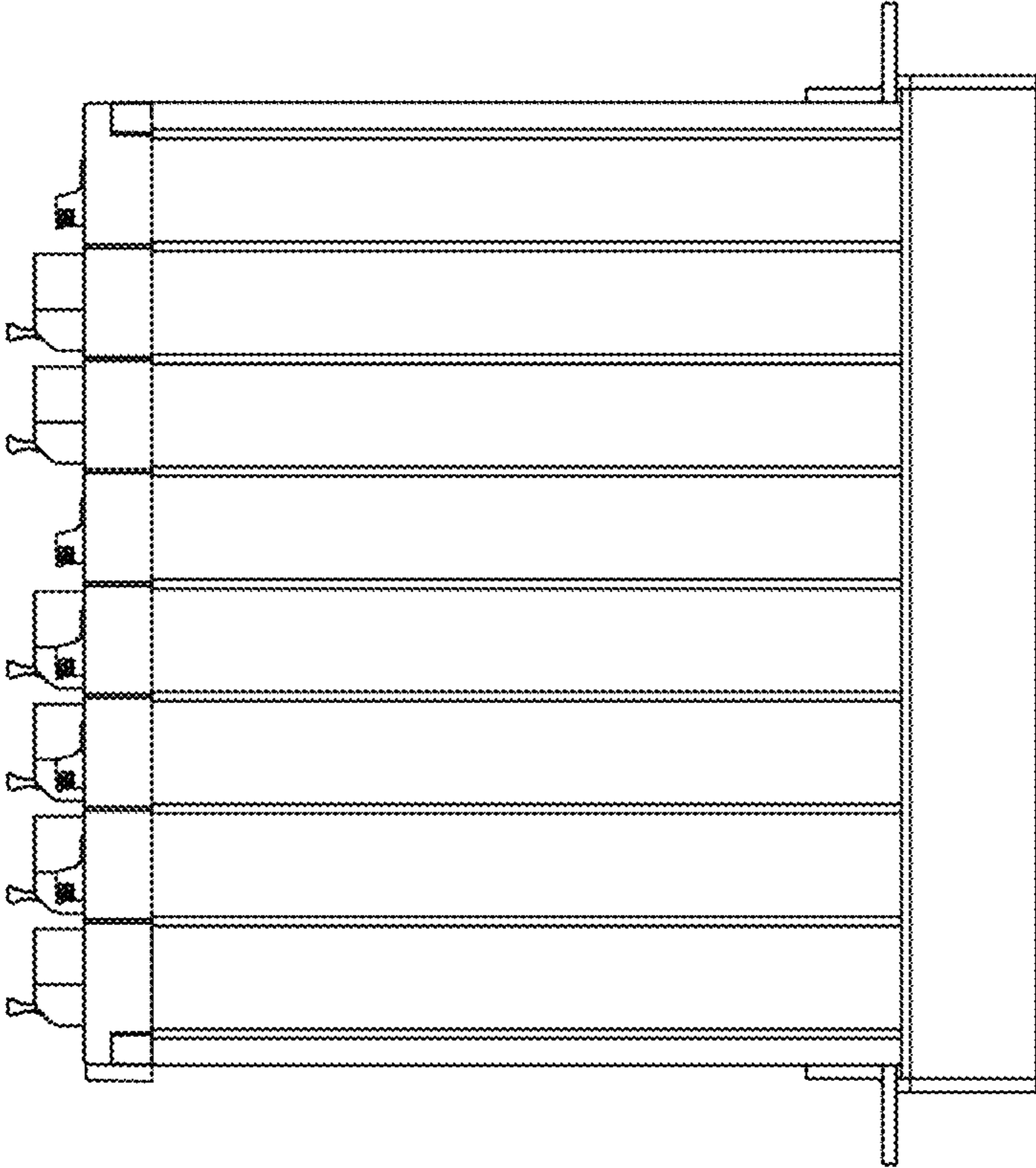


FIG. 7